

**FUNCTIONAL DIAGRAM**

## Octal D-Type Flip-Flop, 3-State Positive-Edge-Triggered

CD54/74AC/ACT564 - Inverting  
CD54/74AC/ACT574 - Non-Inverting

**Type Features:**

- Buffered inputs
- Typical propagation delay:  
6.5 ns @  $V_{CC} = 5V, T_A = 25^\circ C, C_L = 50 pF$

The RCA-CD54/74AC564 and CD54/74AC574 and the CD54/74ACT564 and CD54/74ACT574 octal D-type, 3-state, positive-edge-triggered flip-flops use the RCA ADVANCED CMOS technology. The eight flip-flops enter data into their registers on the LOW-to-HIGH transition of the clock (CP). The Output Enable ( $\overline{OE}$ ) controls the 3-state outputs and is independent of the register operation. When the Output Enable ( $\overline{OE}$ ) is HIGH, the outputs are in the high-impedance state. The CD54/74AC/ACT564 and CD54/74AC/ACT574 share the same pin configurations; the CD54/74AC/ACT564, however, has inverted outputs and the CD54/74AC/ACT574 has non-inverted outputs.

The CD74AC/ACT564 and CD74AC/ACT574 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to +85°C); and Extended Industrial/Military (-55 to +125°C).

The CD54AC/ACT564 and CD54AC/ACT574, available in chip form (H suffix), are operable over the -55 to +125°C temperature range.

**Family Features:**

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST\*/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- ±24-mA output drive current
  - Fanout to 15 FAST\* ICs
  - Drives 50-ohm transmission lines

\*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

**TRUTH TABLE**

INPUTS			OUTPUTS	
			564 $\overline{Q_n}$	574 $Q_n$
$\overline{OE}$	CP	$D_n$	$\overline{Q_n}$	$Q_n$
L		H	L	H
L		L	H	L
L	L	X	$\overline{Q_0}$	$Q_0$
H	X	X	Z	Z

H = High level (steady state)  
L = Low level (steady state)  
X = Don't care  
 = Transition from low to high level  
 $Q_0$  = The level of Q before the indicated steady-state input conditions were established  
 $\overline{Q_0}$  = The level of  $\overline{Q}$  before the indicated steady-state input conditions were established.  
Z = High impedance

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This data sheet is applicable to the CD54/74AC574 and CD54/74ACT574. The CD54/74AC564 and CD54/74ACT564 were not acquired from Harris Semiconductor.

Technical Data

# CD54/74AC564, CD54/74AC574 CD54/74ACT564, CD54/74ACT574

**MAXIMUM RATINGS, Absolute-Maximum Values:**

DC SUPPLY-VOLTAGE ( $V_{CC}$ )	-0.5 to 6 V
DC INPUT DIODE CURRENT, $I_{IK}$ (for $V_i < -0.5$ V or $V_i > V_{CC} + 0.5$ V)	$\pm 20$ mA
DC OUTPUT DIODE CURRENT, $I_{OK}$ (for $V_o < -0.5$ V or $V_o > V_{CC} + 0.5$ V)	$\pm 50$ mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, $I_o$ (for $V_o > -0.5$ V or $V_o < V_{CC} + 0.5$ V)	$\pm 50$ mA
DC $V_{CC}$ or GROUND CURRENT ( $I_{CC}$ or $I_{GND}$ )	$\pm 100$ mA*
POWER DISSIPATION PER PACKAGE ( $P_D$ ):	
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW
OPERATING-TEMPERATURE RANGE ( $T_A$ ):	$-55$ to $+125^\circ\text{C}$
STORAGE TEMPERATURE ( $T_{stg}$ )	$-65$ to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. ( $1.59 \pm 0.79$ mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness $1/16$ in. ( $1.59$ mm) with solder contacting lead tips only	$+300^\circ\text{C}$

\*For up to 4 outputs per device; add  $\pm 25$  mA for each additional output.

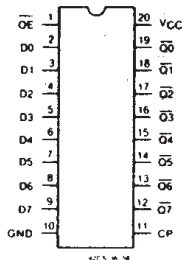
**RECOMMENDED OPERATING CONDITIONS:**

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

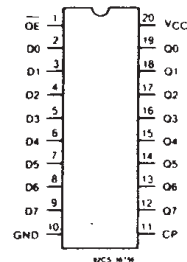
CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, $V_{CC}$ *: (For $T_A =$ Full Package-Temperature Range) AC Types ACT Types	1.5 4.5	5.5 5.5	V V
DC Input or Output Voltage, $V_i, V_o$	0	$V_{CC}$	V
Operating Temperature, $T_A$ :	$-55$	$+125$	$^\circ\text{C}$
Input Rise and Fall Slew Rate, $dt/dv$ at 1.5 V to 3 V (AC Types) at 3.6 V to 5.5 V (AC Types) at 4.5 V to 5.5 V (ACT Types)	0 0 0	50 20 10	ns/V ns/V ns/V

\*Unless otherwise specified, all voltages are referenced to ground.

**TERMINAL ASSIGNMENT DIAGRAMS**



CD54/74AC/ACT564



CD54/74AC/ACT574

# CD54/74AC564, CD54/74AC574 CD54/74ACT564, CD54/74ACT574

**STATIC ELECTRICAL CHARACTERISTICS: AC Series**

CHARACTERISTICS	TEST CONDITIONS		V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C						UNITS
				+25		-40 to +85		-55 to +125		
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V <sub>IH</sub>			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage V <sub>IL</sub>			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.05 -0.05 -0.05 -4 -24 -75 -50	1.5	1.4	—	1.4	—	1.4	—	V
			3	2.9	—	2.9	—	2.9	—	
			4.5	4.4	—	4.4	—	4.4	—	
			3	2.58	—	2.48	—	2.4	—	
			4.5	3.94	—	3.8	—	3.7	—	
			5.5	—	—	3.85	—	—	—	
			5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05 0.05 0.05 12 24 75 50	1.5	—	0.1	—	0.1	—	0.1	V
			3	—	0.1	—	0.1	—	0.1	
			4.5	—	0.1	—	0.1	—	0.1	
			3	—	0.36	—	0.44	—	0.5	
			4.5	—	0.36	—	0.44	—	0.5	
			5.5	—	—	—	1.65	—	—	
			5.5	—	—	—	—	—	1.65	
Input Leakage Current I <sub>I</sub>	V <sub>CC</sub> or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I <sub>oz</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

\*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C. 75 ohms at +125°C.

Technical Data

**CD54/74AC564, CD54/74AC574**  
**CD54/74ACT564, CD54/74ACT574**

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C						UNITS	
				+25		-40 to +85		-55 to +125			
	V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
High-Level Input Voltage	V <sub>IH</sub>		4.5 to 5.5	2	—	2	—	2	—	V	
Low-Level Input Voltage	V <sub>IL</sub>		4.5 to 5.5	—	0.8	—	0.8	—	0.8	V	
High-Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub> #, *	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
			-24	4.5	3.94	—	3.8	—	3.7	—	
			-75	5.5	—	—	3.85	—	—	—	
			-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub> #, *	0.05	4.5	—	±0.1	—	±1	—	±1	V
			24	4.5	—	0.36	—	0.44	—	0.5	
			75	5.5	—	—	—	1.65	—	—	
			50	5.5	—	—	—	—	1.65	—	
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	5.5	—	±0.1	—	±1	—	±1	μA	
3-State Leakage Current	I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND	5.5	—	±0.5	—	±5	—	±10	μA	
Quiescent Supply Current, MSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	4.5 to 5.5	—	2.4	—	2.8	—	3	mA	

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

\*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOADS*
D, OE	0.7
CP	1.17

\*Unit load is ΔI<sub>CC</sub> limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

# CD54/74AC564, CD54/74AC574 CD54/74ACT564, CD54/74ACT574

**PREREQUISITE FOR SWITCHING: AC Series**

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Clock Pulse Width	t <sub>w</sub>	1.5	44	—	50	—	ns
		3.3*	4.9	—	5.6	—	
		5†	3.5	—	4	—	
Setup Time Data to Clock	t <sub>su</sub>	1.5	2	—	2	—	ns
		3.3	2	—	2	—	
		5	2	—	2	—	
Hold Time Data to Clock	t <sub>h</sub>	1.5	2	—	2	—	ns
		3.3	2	—	2	—	
		5	2	—	2	—	
Maximum Clock Frequency	f <sub>MAX</sub>	1.5	11	—	10	—	MHz
		3.3	101	—	89	—	
		5	143	—	125	—	

\*3.3 V: min. is @ 3 V

†5 V: min. is @ 4.5 V

**SWITCHING CHARACTERISTICS: AC Series; t<sub>r</sub>, t<sub>f</sub> = 3 ns, C<sub>L</sub> = 50 pF**

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Clock to Q	t <sub>PLH</sub> t <sub>PHL</sub>	1.5	—	123	—	135	ns
		3.3*	4	13.7	3.8	15.1	
		5†	2.9	9.8	2.7	10.8	
Clock to Q̄	t <sub>PLH</sub> t <sub>PHL</sub>	1.5	—	128	—	141	ns
		3.3	4.1	14.4	4	15.8	
		5	2.9	10.3	2.8	11.3	
Output Enable to Q, Q̄	t <sub>PZL</sub> t <sub>PZH</sub>	1.5	—	165	—	181	ns
		3.3	5.6	19.2	5.5	21.8	
		5	3.7	13.2	3.6	14.5	
Output Disable to Q, Q̄	t <sub>PLZ</sub> t <sub>PHZ</sub>	1.5	—	165	—	181	ns
		3.3	4.7	16.5	4.5	18.1	
		5	3.7	13.2	3.6	14.5	
Power Dissipation Capacitance	C <sub>PD</sub> §	—	67 Typ.		67 Typ.		pF
Min. (Valley) V <sub>OH</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OHV</sub> See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V <sub>OL</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OLP</sub> See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C <sub>i</sub>	—	—	10	—	10	pF
3-State Output Capacitance	C <sub>o</sub>	—	—	15	—	15	pF

\*3.3 V: min. is @ 3.6 V  
max. is @ 3 V

†5 V: min. is @ 5.5 V  
max. is @ 4.5 V

§C<sub>PD</sub> is used to determine the dynamic power consumption, per flip flop.

$$P_D = C_{PD} V_{CC}^2 f_i + \sum V_{CC}^2 f_o C_L$$

where f<sub>i</sub> = input frequency  
f<sub>o</sub> = output frequency  
C<sub>L</sub> = output load capacitance  
V<sub>CC</sub> = supply voltage.

Technical Data

**CD54/74AC564, CD54/74AC574**  
**CD54/74ACT564, CD54/74ACT574**

PREREQUISITE FOR SWITCHING: ACT Series

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Clock Pulse Width	t <sub>w</sub>	5†	3.9	—	4.5	—	ns
Setup Time Data to Clock	t <sub>su</sub>	5	2	—	2	—	ns
Hold Time Data to Clock	t <sub>h</sub>	5	2.6	—	3	—	ns
Maximum Clock Frequency	f <sub>MAX</sub>	5	125	—	110	—	MHz

†5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: ACT Series; t<sub>r</sub>, t<sub>f</sub> = 3 ns, C<sub>L</sub> = 50 pF

CHARACTERISTICS	SYMBOL	V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Clock to Q ACT574	t <sub>PLH</sub> t <sub>PHL</sub>	5†	2.9	10.2	2.8	11.2	ns
Clock to Q̄ ACT564	t <sub>PLH</sub> t <sub>PHL</sub>	5	3	10.6	2.9	11.7	ns
Output Enable and Disable to Q ACT574	t <sub>PLZ</sub> t <sub>PHZ</sub> t <sub>PZL</sub> t <sub>PZH</sub>	5	3.7	13.2	3.6	14.5	ns
Output Enable and Disable to Q̄ ACT564	t <sub>PLZ</sub> t <sub>PHZ</sub> t <sub>PZL</sub> t <sub>PZH</sub>	5	3.7	13.2	3.6	14.5	ns
Power Dissipation Capacitance	C <sub>PD</sub> §	—	67 Typ.		67 Typ.		pF
Min. (Valley) V <sub>OH</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OHV</sub> See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V <sub>OL</sub> During Switching of Other Outputs (Output Under Test Not Switching)	V <sub>OLP</sub> See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C <sub>I</sub>	—	—	10	—	10	pF
3-State Output Capacitance	C <sub>O</sub>	—	—	15	—	15	pF

†5 V: min. is @ 5.5 V  
 max. is @ 4.5 V

§C<sub>PD</sub> is used to determine the dynamic power consumption, per flip flop.

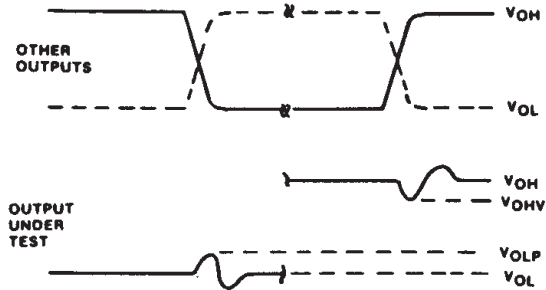
$$P_D = C_{PD} V_{CC}^2 f_i + \sum V_{CC}^2 f_o C_L + V_{CC} \Delta I_{CC}$$

where f<sub>i</sub> = input frequency  
 f<sub>o</sub> = output frequency  
 C<sub>L</sub> = output load capacitance  
 V<sub>CC</sub> = supply voltage.

Technical Data

# CD54/74AC564, CD54/74AC574 CD54/74ACT564, CD54/74ACT574

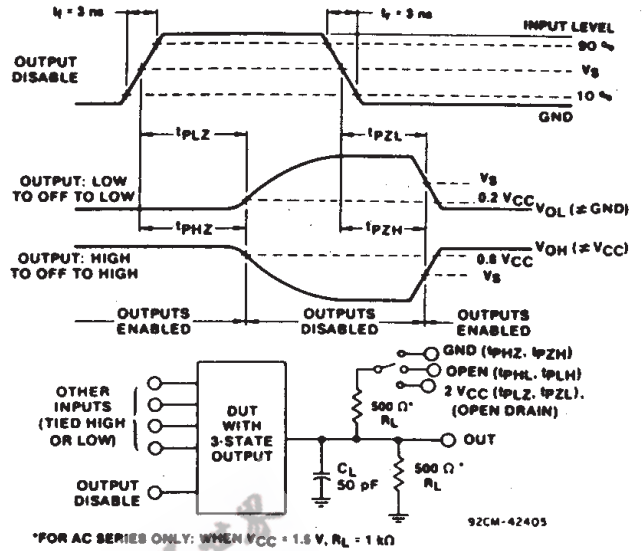
### PARAMETER MEASUREMENT INFORMATION



**NOTES:**

1.  $V_{OHV}$  AND  $V_{OLP}$  ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:  
 $PRR \leq 1$  MHz,  $t_r = 3$  ns,  $t_f = 3$  ns, SKEW 1 ns.
3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED. IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH 0.1  $\mu$ F CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

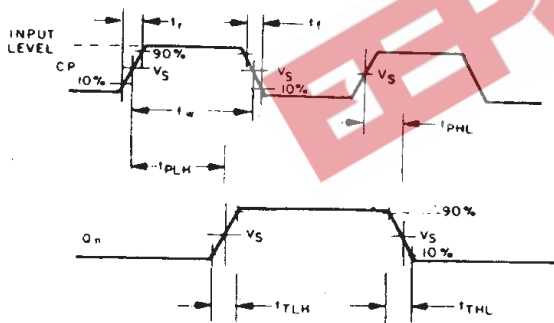
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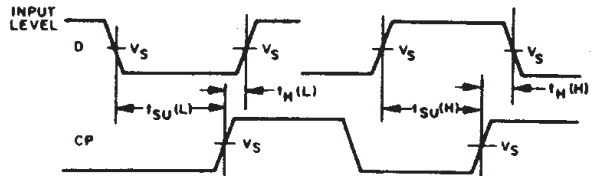
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Fig. 1 - Simultaneous switching transient waveforms.

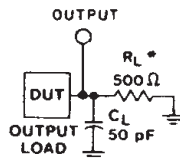
Fig. 2 - Three-state propagation delay waveforms and test circuit.



92CS-38404R1



92CS-38954R1



\*FOR AC SERIES ONLY: WHEN  $V_{CC} = 1.5$  V,  $R_L = 1$  k $\Omega$

92CS-42189

	CD54/74AC	CD54/74ACT
Input Level	$V_{CC}$	3 V
Input Switching Voltage, $V_S$	$0.5 V_{CC}$	1.5 V
Output Switching Voltage, $V_S$	$0.5 V_{CC}$	$0.5 V_{CC}$

Fig. 3 - Propagation delays times and test circuit.



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